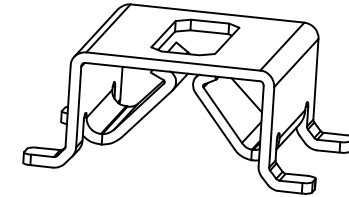
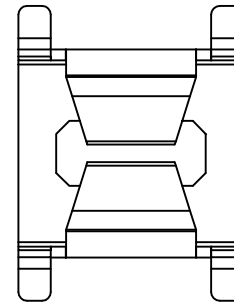
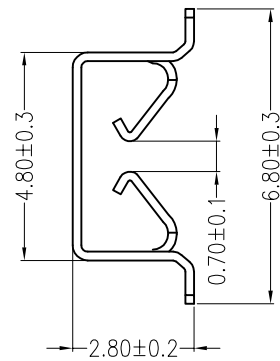
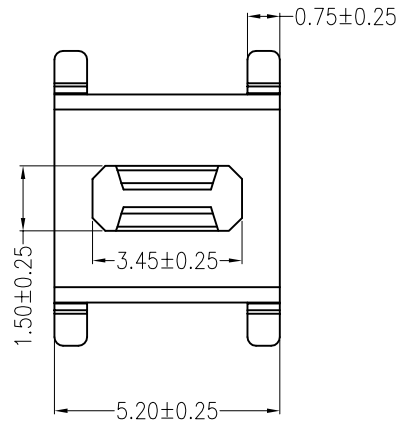


REV	DESCRIPTION	DESIGN	DATE
A0	Release	吴丹平	2016.04.30



主要技术参数 Main Specifications

板 厚 (thickness): 1.0mm
 接触电阻 (Contact resistance): $\leq 20m\Omega$
 绝缘电阻 (Insulation resistance): $\geq 800M\Omega$
 额定电压 (Rated voltage): 250 V AC DC
 额定电流 (Rated current): 1.0A AC DC
 耐 电 压 (Withstand Voltage): 1500V AC/minute
 温度范围 (Temperature Range): $-45^{\circ}C \sim +125^{\circ}C$

ORDER INFORMATION:

L031-1.0-T2CB-R

PART No.

No. FOR PCB:

1.0mm

PLASTIC MATERIAL:

T2C=PBR(BEIGE)

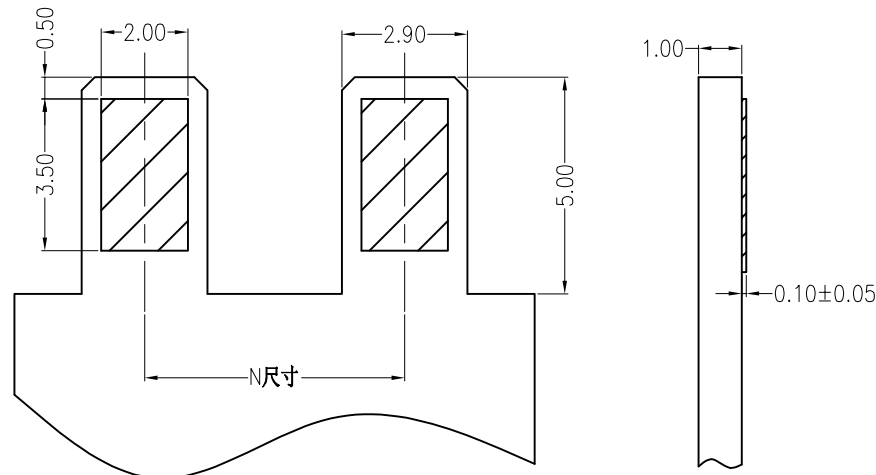
PACKAGING:

R=REEL

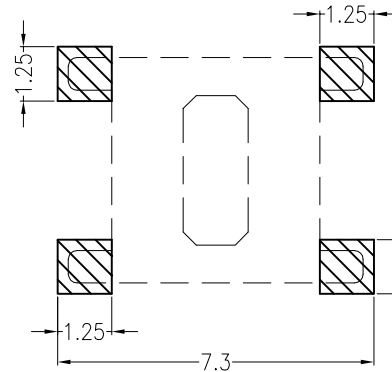
P=PE

PLATING:

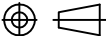
B=MATTE Sn



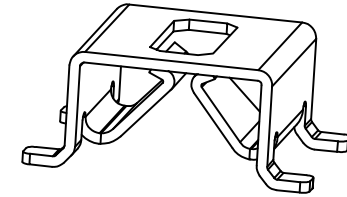
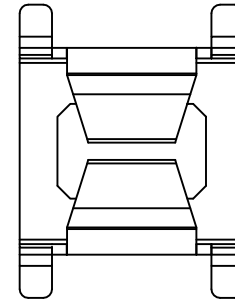
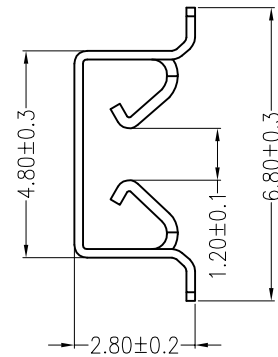
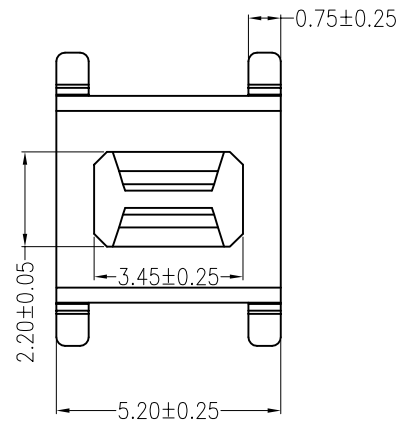
Mating PCB detail



Board Layout

C					
B					
A	CONTACT		1 PCS	PhosphorBronze	MATTE Sn-plated
ITEM	COMPONENT		Q'TY	MATERIAL	FINISH
 东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				TITLE: -	
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:		
.X±0.3	.X±2'		L031-1.0-T2CB-R		
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:		
--	--	CHKD: 田峰	GCCP-0055		
	UNITS: mm	DR: 蒋建银	SCALE		SHEET
			1 : 1		
					1 / 1

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	李润	2016.04.19

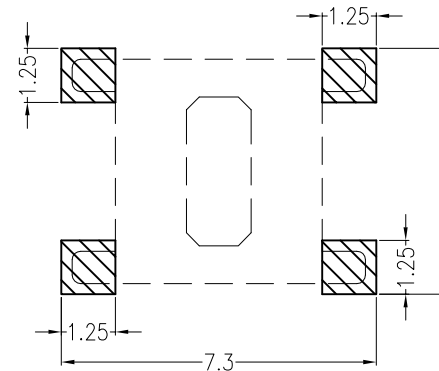


主要技术参数 Main Specifications

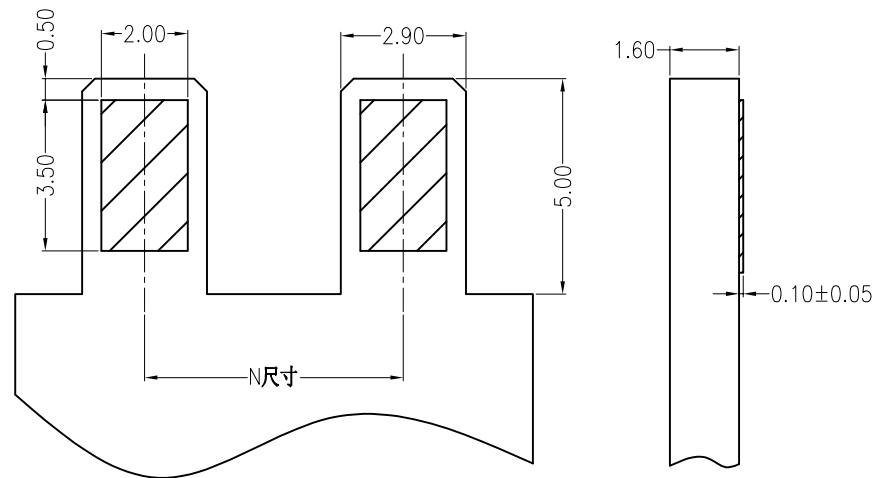
板 厚 (thickness): 1.6mm
接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
绝缘电阻 (Insulation resistance):
额定电压 (Rated voltage): 250 V AC DC
额定电流 (Rated current): 1.0A AC DC
耐 电 压 (Withstand Voltage):
温度范围 (Temperature Range):

ORDER INFORMATION:

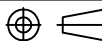
L031-1.6-01-T2CB-R			
PART No.			PACKAGING: R=REEL P=PE
No. FOR PCB: 1.6mm			PLATING: B=MATTE Sn PLASTIC MATERIAL: T2C=PBR (BEIGE)
No. FOR CIRCUITS: 01			



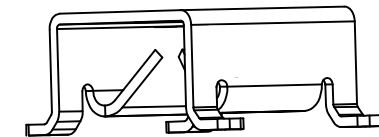
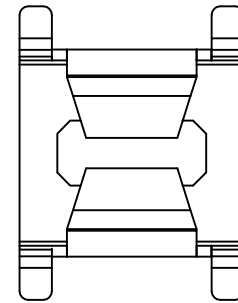
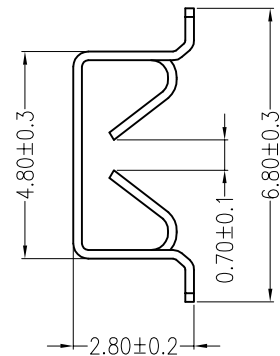
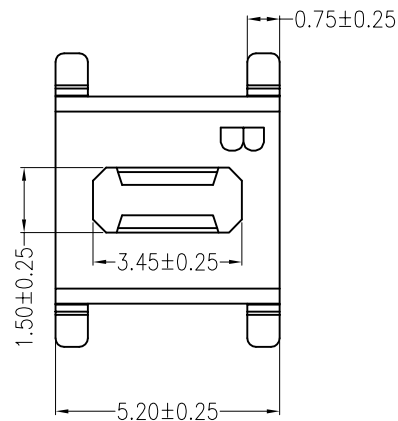
Board Layout



Mating PCB detail

C				
B				
A	CONTACT	1 PCS	PHOSPHORBRONZE	MATTE Sn-plated
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
 东莞市高迪电子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				TITLE: - -
X.±0.5	X.±5°	USE: CUSTOMER APPD: 邵敬和 CHKD: 田峰 DR: 吴丹平	PART NO.: L031-1.6-01-T2CB-R	
.X±0.3	.X±2°		DWG NO.: GCCP-0229	
.XX±0.25	.XX±1°		SCALE 1 : 1	
--	--		SHEET 1 / 1	
	UNITS: mm			

	E		F	
REV	ECN No.	DESCRIPTION	DESIGN	DATE
AO		Release	吴丹平	2017.08.12



主要技术参数 Main Specifications

板 厚 (thickness): 1.0mm

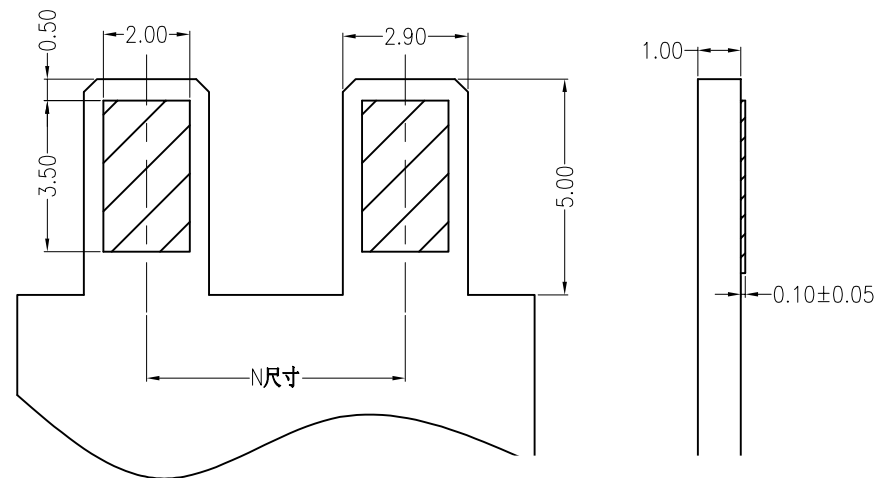
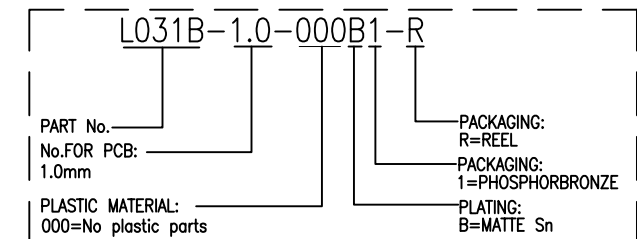
接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$

额定电压 (Rated voltage): 250 V AC DC

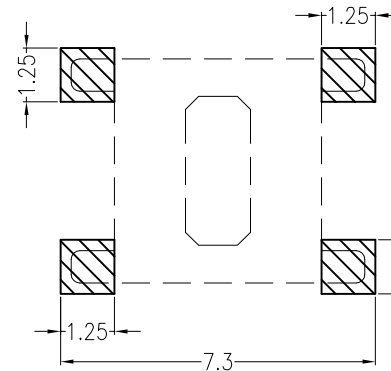
额定电流 (Rated current): 1.0A AC DC

温度范围 (Temperature Range) : $-45^{\circ}\text{C} \sim +125^{\circ}\text{C}$

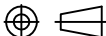
ORDER INFORMATION:



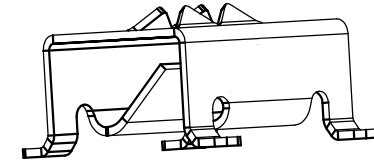
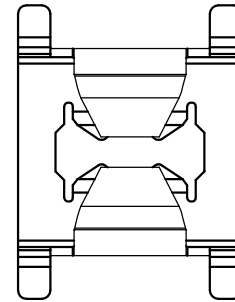
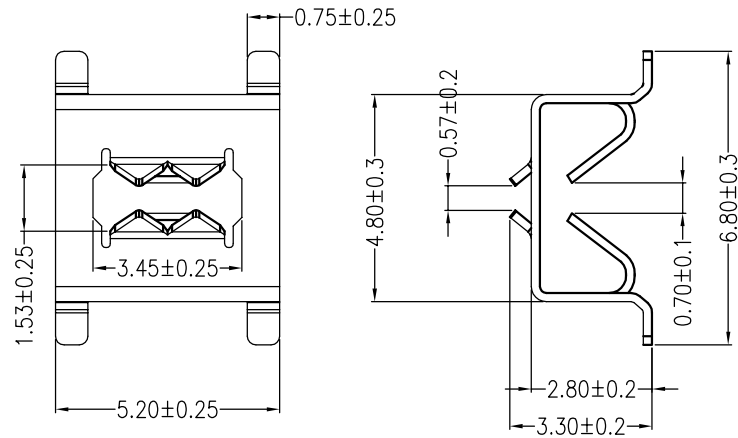
Mating PCB detail



Board Layout

C					
B					
A	CONTACT		1 PCS	PHOSPHORBRONZE	MATTE Sn-plated
ITEM	COMPOENEN		Q'TY	MATERIAL	FINISH
 東莞市高迪電子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD					TITLE: - -
X.±0.5	X.±5'	USE: CUSTOMER	PART NO.:		
X.±0.3	X.±2'		L031B-1.0-000B1-R		
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:		
--	--	CHKD: 田峰	GCCP-1022		
	UNITS: mm	DR: 吴丹平	SCALE		SHEET
			1 : 1		

REV	ECN No.	DESCRIPTION	DESIGN	DATE
A0		Release	曾令青	2018.08.24

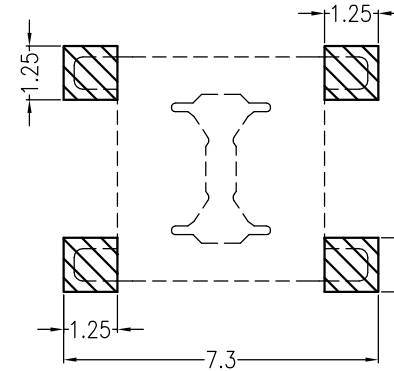


主要技术参数 Main Specifications

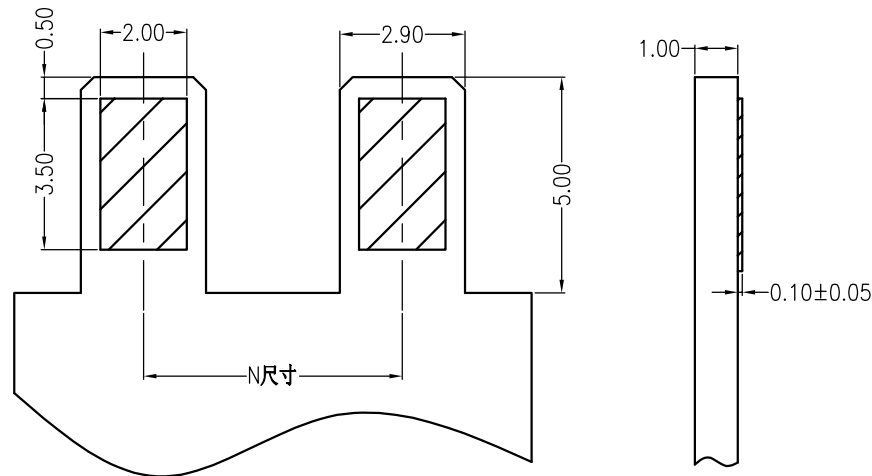
板 厚 (thickness): 1.0mm
接触电阻 (Contact resistance): $\leq 20\text{m}\Omega$
额定电压 (Rated voltage): 250 V AC DC
额定电流 (Rated current): 1.0A AC DC
温度范围 (Temperature Range): $-45^{\circ}\text{C} \sim +125^{\circ}\text{C}$

ORDER INFORMATION:

L031C-1.0-000B1-R			
PART No.		PACKAGING:	R=REEL
No.FOR PCB:		PACKAGING:	1=PHOSPHORBRONZE
1.0mm		PLATING:	B=MATTE Sn
PLASTIC MATERIAL:			
000=No plastic parts			



Board Layout



Mating PCB detail

C				
B				
A	CONTACT	1 PCS	PHOSPHORBRONZE	MATTE Sn-plated
ITEM	COMPONENT	Q'TY	MATERIAL	FINISH
東莞市高迪電子有限公司 DONG GUAN GAO DI ELECTRONICS CO., LTD				TITLE: -
X.±0.5	X.±5'	USE:	PART NO.:	
.X±0.3	.X±2'	CUSTOMEP	L031C-1.0-000B1-R	
.XX±0.25	.XX±1'	APPD: 邵敬和	DWG NO.:	
--	--	CHKD: 田峰	GCCP-1226	
⊕	UNITS: mm	DR: 曾令青	SCALE	SHEET
			1 : 1	1 / 1